

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



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GDT



PLED

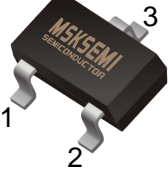
2SC4617x-MS

Product specification

Applications

- Low Cob:Cob=2.0pF(Typ)
- Complement to 2SA1774x-MS

Reference News

SOT-523	
	1. BASE 2. EMITTER 3. COLLECTOR

Marking

2SC4617Q-MS	2SC4617R-MS	2SC4617S-MS
BQ	BR	BS

MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Parameter	Value	Unit
Collector-Base Voltage	60	V
Collector-Emitter Voltage	50	V
Emitter-Base Voltage	7	V
Collector Current -Continuous	150	mA
Collector Power Dissipation	150	mW
Operation Junction and Storage Temperature Range	-55-150	°C

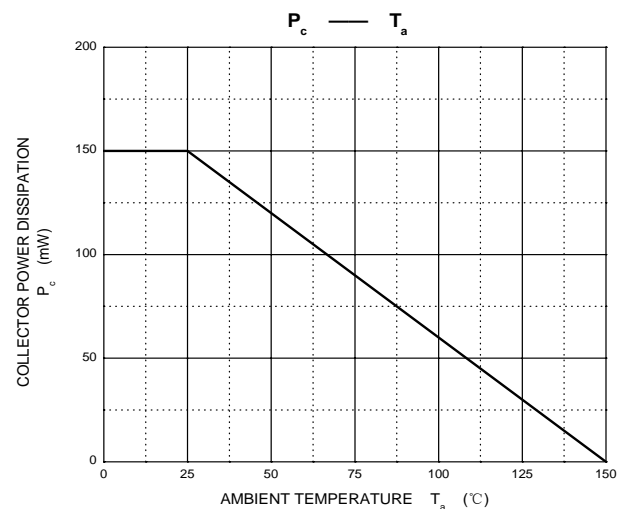
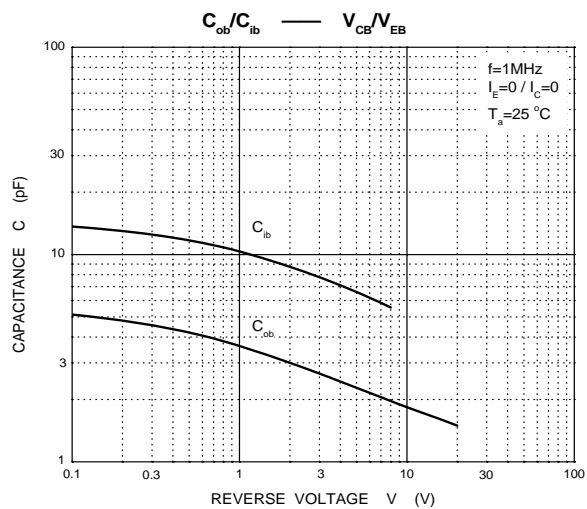
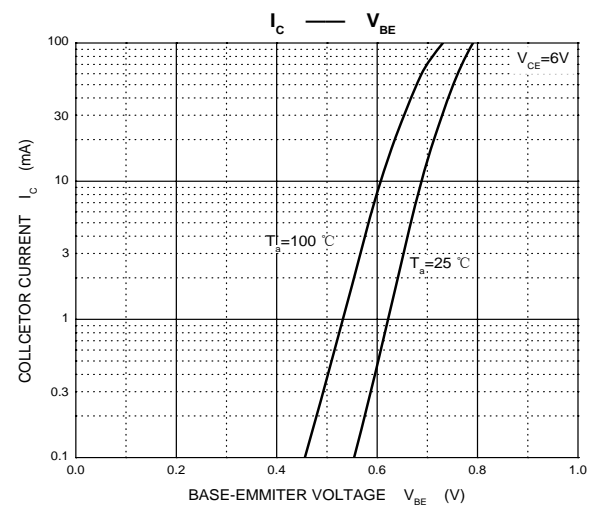
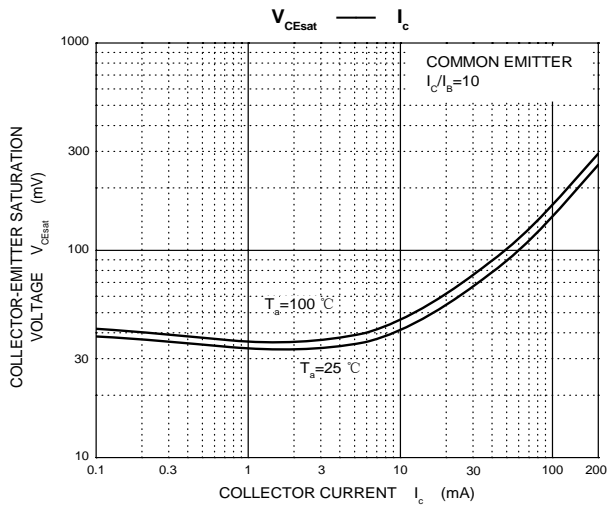
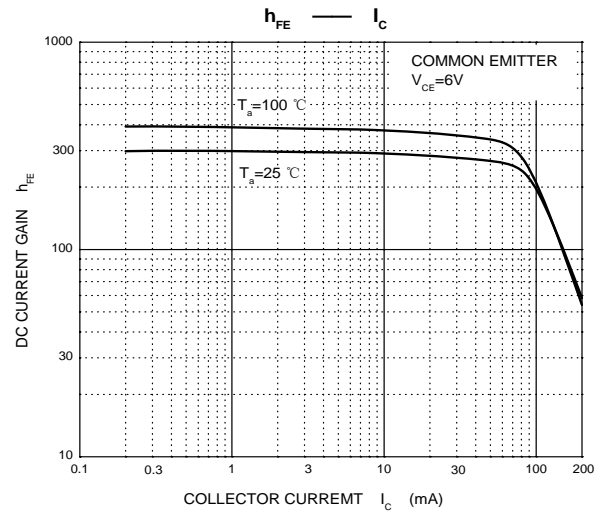
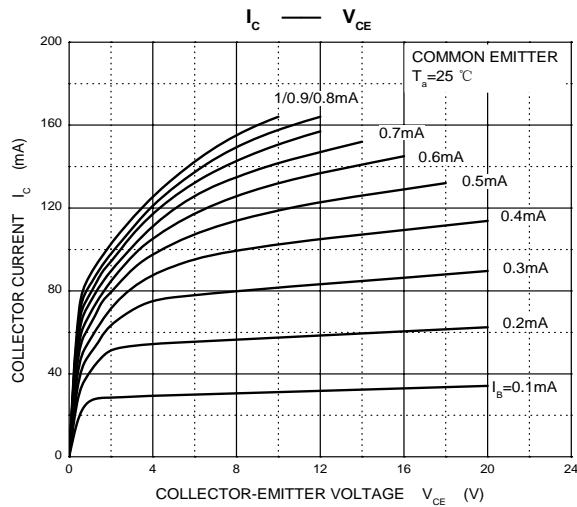
ELECTRICAL CHARACTERISTICS (T_a=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =50uA, I _E =0	60			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =1mA, I _B =0	50			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =50uA, I _C =0	7			V
Collector cut-off current	I _{CBO}	V _{CB} =60V, I _E =0			0.1	μA
Emitter cut-off current	I _{EBO}	V _{EB} =7V, I _C =0			0.1	μA
DC current gain	h _{FE}	V _{CE} =6V, I _C =1mA	120		560	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =50mA, I _B =5mA			0.4	V
Transition frequency	f _T	V _{CE} =12V, I _C =2mA, f=100MHz		180		MHz
Collector output capacitance	C _{ob}	V _{CB} =12V, I _E =0, f=1MHz			3.5	pF

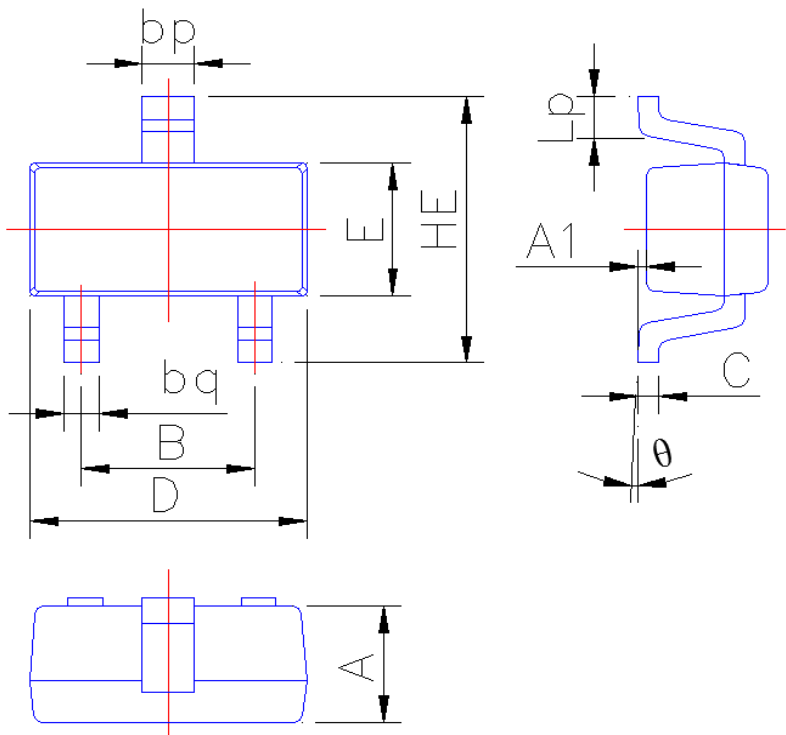
CLASSIFICATION OF h_{FE}

Rank	2SC4617Q-MS	2SC4617R-MS	2SC4617S-MS
Range	120-270	180-390	270-560

Typical Characteristics



PACKAGE MECHANICAL DATA



SOT-523

Symbol	Dimension in Millimeters	
	Min	Max
A	0.60	0.80
A1	0.010	0.100
B	0.95	1.05
bp	0.26	0.40
bq	0.16	0.30
C	0.09	0.15
D	1.50	1.70
E	0.70	0.85
HE	1.45	1.75
Lp	0.16	0.36
θ	0°	5°

REELSPECIFICATION

P/N	PKG	QTY
2SC4617x-MS	SOT-523	3000

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